AMENDMENTS TO THE CLAIMS:

1. (Currently amended) An apparatus for polishing a substrate, comprising:

a roll;

a first polishing pad, to be wound by said roll, for polishing a substrate;

a motor connected to said roll for taking up said first polishing pad;

a sensor for detecting wear of said first polishing pad; and

a controller for energizing said motor according to a signal from said sensor.

2. (Original) The apparatus according to claim 1, further comprising a brush for removing ground-off material produced during a polishing process.

3. (Currently amended) The apparatus according to claim 1, further comprising an atomizer for spraying a gas-liquid mixture onto said first polishing pad.

4. (Original) The apparatus according to claim 1, further comprising an optical sensor for monitoring thickness of a film of the substrate.

5. (Currently amended) The apparatus according to claim 1, wherein said first polishing pad is mounted on a first polishing table, and further comprising a second polishing pad ~~is~~ mounted on a second polishing table.

6. (Currently amended) The apparatus according to claim 5, wherein said first polishing pad ~~mounted on said first polishing table~~ comprises a fixed abrasive pad.

7. (Currently amended) The apparatus according to claim 5, wherein said second polishing pad ~~mounted on said second polishing table~~ comprises a polyurethane foam pad.

8. (Original) An apparatus for polishing a substrate, comprising:

a roll;

a polishing pad, to be wound by said roll, for polishing a substrate;

a motor connected said roll for taking up said polishing pad;

a sensor for detecting a condition of said polishing; and

a controller for energizing said motor according to a signal from said sensor.

Claims 9-10 (cancelled)

11. (Original) A method of treating a substrate, comprising:

polishing a substrate by pressing said substrate against a polishing pad which is wound on a roll;

detecting wear of said polishing pad by a sensor;

sending a signal to a controller; and

taking up said polishing pad after said controller receives said signal.

12. (Original) The method according to claim 11, wherein sending of said signal is performed when said sensor detects said wear of said polishing pad.

13. (Original) The method according to claim 11, wherein said taking up of said polishing pad is performed by a motor energized by said controller.

14. (Original) The method according to claim 11, further comprising:

applying ultra violet radiation for deteriorating said polishing pad.

15. (Original) The method according to claim 11, further comprising:

applying electromagnetic waves for measuring thickness a film of said substrate.